



Material Content Data Sheet



Sales Product Name				IPU60R2K0C6		Issued		29. August 2013	
MA#				MA000986848					
Package				PG-TO251-3-341		Weight*		380.87 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.272	0.33	0.33	3339	3339	
leadframe	non noble metal	iron	7439-89-6	0.248	0.07		652		
	inorganic material	phosphorus	7723-14-0	0.075	0.02		196		
	non noble metal	copper	7440-50-8	248.124	65.16	65.25	651468	652316	
wire	non noble metal	aluminium	7429-90-5	0.468	0.12	0.12	1229	1229	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.747	0.46		4588		
	plastics	brominated resin	-	1.872	0.49		4915		
	organic material	carbon black	1333-86-4	1.997	0.52		5243		
	plastics	epoxy resin	-	16.849	4.42		44238		
	inorganic material	silicondioxide	60676-86-0	102.342	26.87	32.76	268706	327690	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9820	9820	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1336	1336	
solder	noble metal	silver	7440-22-4	0.041	0.01		107		
	non noble metal	tin	7440-31-5	0.033	0.01		85		
	non noble metal	lead	7439-92-1	1.553	0.41	0.43	4078	4270	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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